

#### DESCRIPTION

The SPN1026 is the Dual N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 320mA DC and can deliver pulsed currents up to 1.0A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

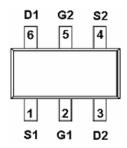
### **APPLICATIONS**

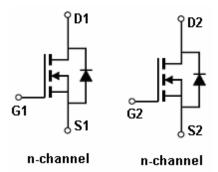
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

#### **FEATURES**

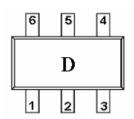
- $\bullet$  60V/0.50A, RDS(ON)= 3.5 $\Omega$ @VGS=10V
- 60V/0.30A, RDS(ON)=  $4.5\Omega$ @VGS=5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOT-563 / SC-89-6L package design

### PIN CONFIGURATION(SOT-563/SC-89-6L)





### **PART MARKING**



## **PIN DESCRIPTION**

Pin	Symbol	Description
1	S1	Source 1
2	G1	Gate 1
3	D2	Drain 2
4	S2	Source 2
5	G2	Gate 2
6	D1	Drain1

## **ORDERING INFORMATION**

Part Number	Package	Part Marking
SPN1026S56RG	SOT-563	D

**%** Week Code :  $A \sim Z(1 \sim 26)$ ;  $a \sim z(27 \sim 52)$ 

% SPN1026S56RG : Tape Reel ; Pb – Free

## **ABSOULTE MAXIMUM RATINGS** (TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	60	V
Gate –Source Voltage - Continuous		VGSS	±20	V
Gate –Source Voltage - Non Repetitive (t <sub>p</sub> < 50μs)		VGSS	±40	V
Continuous Drain Current(TJ=150°C)	TA=25°C	ID	0.32	A
Pulsed Drain Current (*)	Ірм	1.0	A	
Continuous Source Current(Diode Conduction)		Is	0.25	A
Power Dissipation	TA=25°C	PD	0.30	W
Operating Junction Temperature		Тл	<b>-</b> 55 ∼ 150	$^{\circ}\!\mathbb{C}$
Storage Temperature Range		Tstg	<b>-</b> 55 ∼ 150	$^{\circ}\! \mathbb{C}$
Thermal Resistance-Junction to Ambient		RθJA	375	°C/W

(\*) Pulse width limited by safe operating area

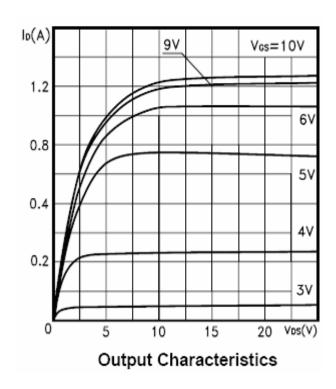
# **ELECTRICAL CHARACTERISTICS** (TA=25°C Unless otherwise noted)

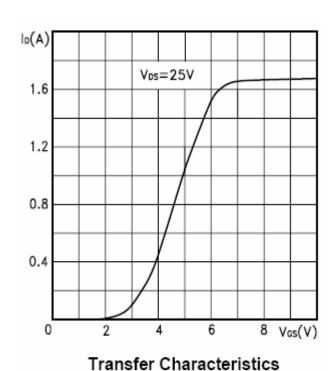
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	<u>l</u>						
Drain-Source Breakdown Voltage	V(BR)DSS	V <sub>GS</sub> =0V,I <sub>D</sub> =250uA	60			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	1.0	1.7	2.5	7 V	
Gate Leakage Current	Igss	VDS=0V,VGS=±20V			±100	nA	
		V <sub>DS</sub> =50V,V <sub>GS</sub> =0V			10	nA	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V T <sub>J</sub> = 85°C			100		
Drain-Source On-Resistance	RDS(on)	Vgs=10V,Id=0.50A		2.8	3.5	Ω	
	` ′	V <sub>GS</sub> = 5V,I <sub>D</sub> =0.30A		3.5	4.5		
Source-drain Current	ISD				0.32	A	
Source-drain Current (pulsed)	IsDM (2)				1.4	A	
Forward Transconductance	Gfs(1)	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		0.6		S	
Diode Forward Voltage	VsD(1)	$V_{GS} = 0 \text{ V}, I_{S} = 0.2A$		0.85	1.5	V	
Dynamic							
Total Gate Charge	Qg			1.4	2.0	nC	
Gate-Source Charge	Qgs	$V_{DD} = 30 \text{ V}, I_{D} = 1 \text{ A}, V_{GS} = 5 \text{ V}$		0.8			
Gate-Drain Charge	Qgd	- V G 5 V		0.5		<b>1</b>	
Input Capacitance	Ciss			43		pF	
Output Capacitance	Coss	$V_{DS} = 25 \text{ V, } f = 1 \text{ MHz,}$ $V_{GS} = 0$		20			
Reverse Transfer Capacitance	Crss	V GS — 0		6		<b>1</b>	
T. O. T.	td(on)			5		ns	
Turn-On Time	tr	$V_{DD} = 30 \text{ V}, I_{D} = 0.5 \text{ A}$		15			
T. OMT.	td(off)	$R_G = 4.7\Omega \text{ VGs} = 4.5 \text{ V}$		7			
Turn-Off Time	tf	]		8			

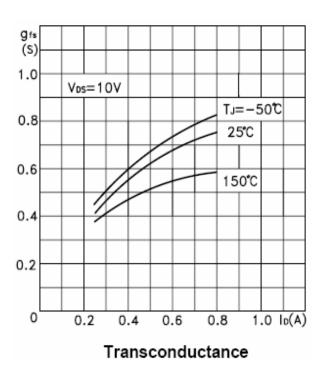
<sup>(1)</sup> Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %.

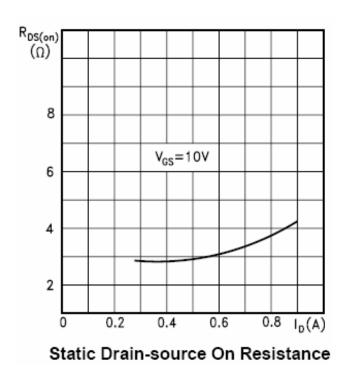
<sup>(2)</sup> Pulse width limited by safe operating area.

## TYPICAL CHARACTERISTICS



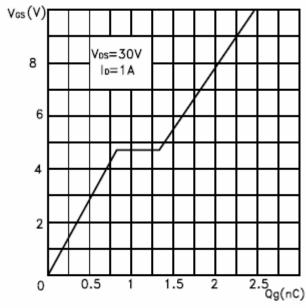




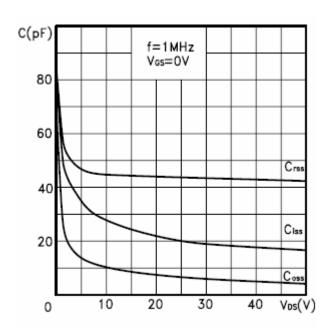




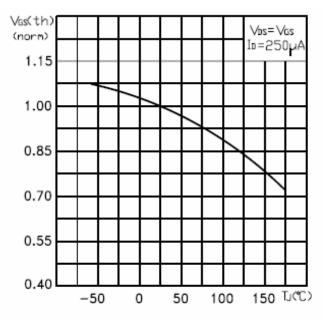
## TYPICAL CHARACTERISTICS



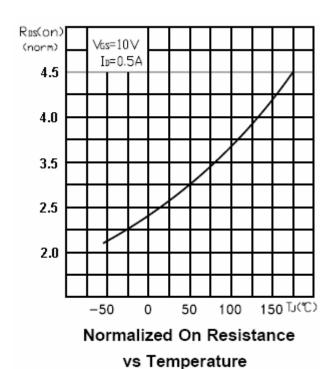
Gate Charge vs Gate-source Voltage



Capacitance Variations



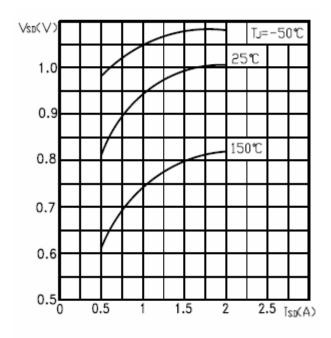
Normalized Gate Threshold Voltage vs Temperature



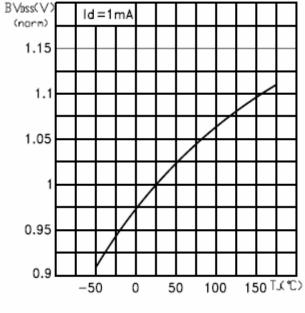
2006/09/30 **Ver.1** Page 5



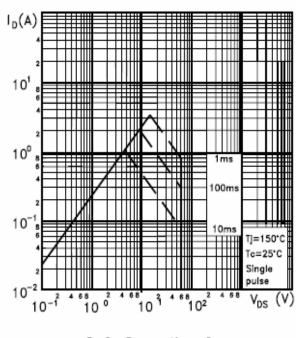
## TYPICAL CHARACTERISTICS



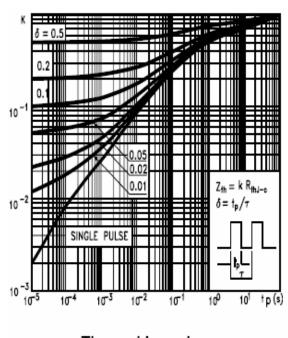
Source-Drain Forward



Normalized BVDSS vs Temperature



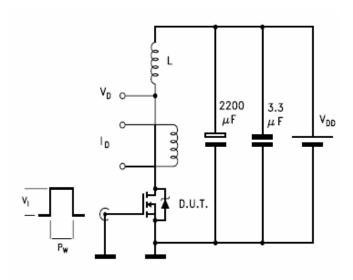
Safe Operating Area



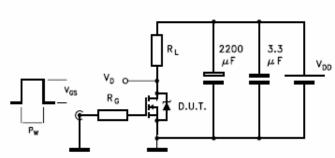
Thermal Impedance

2006/09/30 **Ver.1** 

## TYPICAL TESTING CIRCUIT



Unclamped Inductive Load Test



Switching Times Test Circuit

DIODE

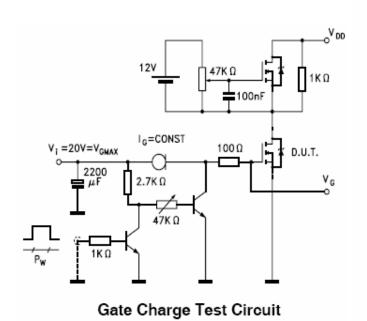
L=100µH

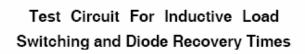
1000

 $V_{DD}$ 

 $\mu$ F

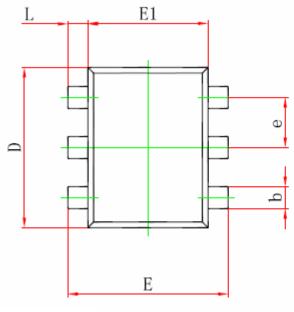
3.3

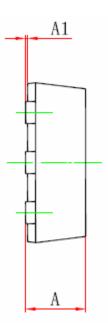


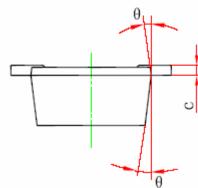




# **SOT-563 PACKAGE OUTLINE**







Symbol	Dimensions in Millimeters		Dimensions in Inches	
Symbol	MIn.	Max.	Min.	Max.
A	0. 525	0.600	0.021	0.024
A1	0.000	0.050	0.000	0.002
e	0.450	0.550	0.018	0.022
С	0.090	0.160	0.004	0.006
D	1.500	1.700	0.059	0.067
b	0.170	0.270	0.007	0.011
E1	1.100	1.300	0.043	0.051
E	1, 500	1.700	0.059	0.067
L	0.100	0.300	0.004	0.012
θ	7 °REF.		7 <sup>0</sup> REF.	

Information provided is alleged to be exact and consistent. SYNC Power Corporation presumes no responsibility for the penalties of use of such information or for any violation of patents or other rights of third parties which may result from its use. No license is granted by allegation or otherwise under any patent or patent rights of SYNC Power Corporation. Conditions mentioned in this publication are subject to change without notice. This publication surpasses and replaces all information previously supplied. SYNC Power Corporation products are not authorized for use as critical components in life support devices or systems without express written approval of SYNC Power Corporation.

©The SYNC Power logo is a registered trademark of SYNC Power Corporation
©2004 SYNC Power Corporation – Printed in Taiwan – All Rights Reserved
SYNC Power Corporation
9F-5, No.3-2, Park Street
NanKang District (NKSP), Taiwan, 115, R.O.C
Phone: 886-2-2655-8178

Fax: 886-2-2655-8468 ©http://www.syncpower.com